

IN THE CLAIMS:

Cancel claims 1-12 and consider claims 13-18.

1-12. (Cancelled)

13. (currently amended) A method of attaching an integrated circuit die to a base carrier comprising the steps of:

dispensing an adhesive material onto a central area of a top surface of the base carrier,

wherein the central area is sized to receive the integrated circuit die and the central area is surrounded by a peripheral area; and

attaching a bottom surface of the integrated circuit die to the central area on the top

surface of the base carrier with the adhesive material, wherein the adhesive material dispensed onto the top surface of the base carrier extends beyond edges of the die a distance greater than about two times a thickness of the die [well into the peripheral area of the base carrier top surface].

14. (original) The method of attaching an integrated circuit die to a base carrier of claim 13, wherein the dispensed adhesive material covers substantially the entire top surface of the base carrier.

15. (original) The method of attaching an integrated circuit die to a base carrier of claim 13, wherein the adhesive material is dispensed onto the base carrier top surface in a predetermined pattern.

16. (original) The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises an "X" pattern.

17. (original) The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises a six point star pattern.

18. (original) The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises an eight point star pattern.